

1.2A 1.5MHz High Efficiency Synchronous-Rectified Step-Down Converter

General Information

The LTS8003 is a synchronous step-down converter with an input voltage range of 2.5V to 5.5V. It delivers up to 1A continuous output current with high efficiency over a wide output current range. At medium to heavy load, the converter operates in fixed 1.5MHz frequency PWM mode and automatically enters power save mode (PSM) operation at light load currents to maintain high efficiency over the entire load current range. The PSM function can be enabled /disabled by a MODE pin.

The output voltage can be regulated as low as 0.6V. The LTS8003 can also run at 100% duty cycle for low dropout applications. A POK# output is available for indicating output voltage status. The device enters shutdown mode and consumes less than 0.1uA when the EN pin is pulled low.

Other features include soft-start, 0.6V internal reference voltage with 2% accuracy, output discharge at shutdown, over temperature protection, and over current protection. The LTS8003 is available in WDNF2x2-6L, WDFN2x2-8L, or TSOT23-6 package.

Applications

- Battery Powered Portable Devices
- Point of Load Regulators
- System Power Rail Voltage Conversion
- Cellular Phones
- **■** Personal Information Appliances

Features

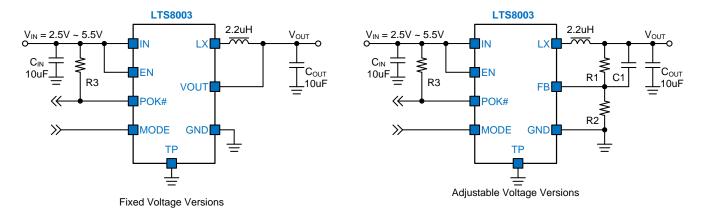
- Wide Input Voltage from 2.5V to 5.5V
- Adjustable Output Voltage form 0.6V to V_{IN}
- 100% Duty Cycle for Lowest Dropout
- 1.2A Output Current
- Up to 95% High Efficiency
- No Schottky Diode Required
- 1.5MHz Fixed Frequency PWM Operation
- Power Save Mode for Light Load Efficiency
- Internal Soft Start
- Output Discharge Function
- **■** Power Good Output
- Space Saving Tiny Package
- RoHS Compliant and Halogen Free

Pin Configuration & Top Marking

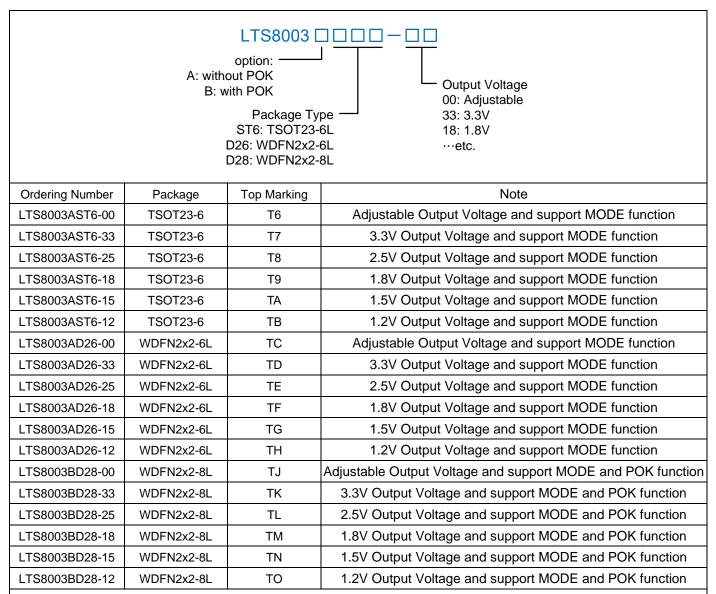
Pin Configuration	Top Marking
EN 11 O 16 FB/VOUT GND 21	PPPP: Product Code YMDS: Date Code
FB/VOUT 11 0/ 16 EN MODE 21 TP 15 GND VIN 31 14 LX WDFN2x2-6L (AD26)	PPPP: Product Code YMDS: Date Code
FB/VOUT 11 0/ 18 EN MODE 21 TP 17 NC POK# 31 TP 16 GND VIN 41 15 LX WDFN2x2-8L (BD28)	PPPP: Product Code YMDS: Date Code



Typical Application Circuit



Ordering Information



Note 1. Leading TECH products are RoHs compliant and compatible with the current requirement of IPC/JDEC J-STD-020 and are suitable for use in SnPb or Pb-Free soldering processes.

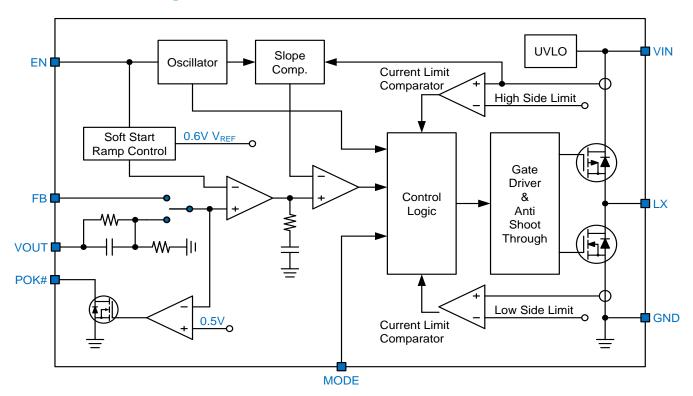
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Functional Pin Descriptions

Pin Number		Pin	Description				
AD26	BD28	AST6	Name	Description			
			VOUT	Output Voltage Sense Pin. For fixed output versions only. Connect this pin the output voltage.			
1	1	6	6	6	6	FB	Output Feedback Pin. For adjustable output versions only. Connect this pin to the center point of the output resistor divider to program the output voltage: $V_{OUT} = 0.6V \times (1 + R1/R2)$. Add optional C1 (10pF ~ 47pF) to speed up transient response.
2	2	5	MODE	Operation Mode Selection. Logic high operates the converter in fixed-frequency PWM mode, logic low in power saving mode (PSM mode). This pin is pulled high by an internal 2uA current source.			
-	3	-	POK#	Power OK Open Drain Output. This pin is pulled to low if the FB voltage exceeds the rising threshold 89% of V _{REF} . Let this pin floating if not used.			
3	4	4	VIN	Power Supply Voltage Input.			
4	5	3	LX	Switch Pin connected to the internal MOSFET switches and inductor terminal. Connect the inductor of the output filter here.			
5	6	2	GND	Power and Signal Ground. Connect externally to thermal pad.			
	7		NC	Not Internally Connected. For WDFN2x2-8L package option only.			
6	8	1	EN	Enable Input. Logic high turns on the converter. Do not let floating.			
7	9	х	TP	Thermal Pad. Internally connected to GND; used to heat-sink the part to the circuit board traces. Connect the thermal pad to ground plane or island with multiple through holes.			

Functional Block Diagram





Operation Principles

The LTS8003 is a synchronous step-down converter with an input voltage range of 2.5V to 5.5V. It delivers up to 1A continuous output current with high efficiency over a wide output current range. At medium to heavy load, the converter operates in PWM mode and automatically enters power save mode operation at light load currents to maintain high efficiency over the entire load current range.

The output voltage can be output voltage can be regulated as low as 0.6V. The LTS8003 can also run at 100% duty cycle for low dropout applications. The device enters shutdown mode and consumes less than 0.1uA when the EN pin is pulled low.

To address the requirements of system power rail, the internal compensation circuit allows a large selection of external capacitor values ranging from 4.7uF up to 100uF effective capacitance.

Other features include soft-start, 0.6V internal reference voltage with 2% accuracy, over temperature protection, and over current protection. The LTS8003 is available in TSOT23-5 or WDFN2x2-6L package.

Supply Input & Under Voltage Lockout (UVLO)

The LTS8003 operates with a wide input voltage range between 2.5V to 5.5V. The input voltage is continuously monitored for under voltage lockout (UVLO). UVLO shuts down the converter if the input voltage is lower than 2.4V threshold level.

The LTS8003 draws pulsed current with sharp edges each time the upper switch turns on, resulting in voltage ripples and spikes at supply input. A minimum 4.7uF ceramic capacitor with shortest PCB trace is highly recommended for bypassing the supply input.

Chip Enabling / Disabling & Soft Start

Logic low at EN input shuts down the converter and reduces its quiescent to less than 1uA. In shutdown mode, both upper and lower switches are turned off.

Pulling the EN pin higher than 1.4V enables the converter and initiates the soft start cycle. The internal soft start circuitry controls output voltage ramping-up time (100us) to limits the inrush current at start-up. This prevents unwanted shutdown otherwise may be triggered by voltage drop due to large inrush current.

PWM Operation

The LTS8003 adopts slope-compensated, current mode PWM control capable of achieving 100% duty cycle. During normal operation, the LTS8003 operates at PWM mode to regulate output voltage by transferring the input power to the output voltage cycle by cycle at a constant 1.5MHz frequency.

The LTS8003 turns on the upper switch at each rising edge of the internal clock allowing the inductor current to ramp up linearly. The upper switch remains on until either the current-limit is tripped or the PWM comparator turns off the switch for regulating the output voltage. After the upper switch turns off, the lower switch turns on and freewheels the inductor current until the rising edge of next clock. The inductor current ramps down linearly when upper switch turns off.

The LTS8003 regulates the output voltage by controlling the ramp up/down duty cycle of inductor current. The upper switch current is sensed, slope compensated and compared with the error amplifier output COMP to determine the adequate duty cycle. When the load current increases, it causes a slight decrease in the feedback voltage relative to the 0.6V reference, which in turn, causes the COMP voltage to increase until the average inductor current matches the new load current.

Power Saving Mode (PSM) Operation

A **Diode Emulator** monitors inductor current by sensing voltage drop across the lower switch when it turns on. The lower switch turns off when inductor current zero crossing is detected to emulate the free wheel diode used in traditional asynchronous buck converter. This operates the converter in discontinuous conduction mode and allows the converter entering power saving mode (PSM) at light load condition.

In PSM mode, the LTS8003 operate in pulse frequency modulation (PFM) with reduced switching frequency, reducing conduction and switching losses and maintaining high efficiency with minimum quiescent current.

The PSM operation can be disabled by connecting the MODE pin the high level.



100% Duty Cycle Low Dropout Mode

The LTS8003 increases duty cycle to maintain output voltage within regulation as the supply input drops gradually in battery-power application. The LTS8003 operates with 100% duty cycle and enters low dropout mode as the supply input approaches the output voltage. This maximizes the operation time by taking full advantage of the whole battery voltage range.

Output Voltage Setting and Feedback Network

For the adjustable versions, the output voltage can be set from V_{REF} to V_{IN} by voltage dividers as:

$$V_{OUT} = V_{REF} \times \frac{R1 + R2}{R2}$$

The internal V_{REF} is 0.6V with 2% accuracy. For best accuracy, R2 should be kept smaller than $40k\Omega$ to ensure that the current flowing through R2 is at least 100 times larger than I_{FB} . Changing the sum towards a lower value increases the robustness against noise injection. Changing the sum towards higher values reduces the quiescent current.

In real applications, a 22pF feedforward ceramic capacitor is recommended in parallel with R2 for better transient response. The feedforward is internally implemented for the fixed voltage versions.

POK# Output

POK# is an open-drain output that indicates whether the output voltage is ready or not. POK# is typically pulled up to system I/O voltage level or tied with VIN directly. POK# is in low impedance when the voltage on FB pin exceeds the rising threshold 89% of V_{REF} . POK# is in high impedance when the voltage on FB pin falls below the falling threshold 86% of V_{REF} . If the voltage detector feature is not required, let this pin at floating state.

Output Discharge

The output gets discharged by the LX pin with a typical discharge resistor of R_{DIS} whenever the device shuts down. This is the case when the device gets disabled by enable, thermal shutdown trigger, and undervoltage lockout trigger.

Current Limit

Both upper and lower switches are short-circuit protected with maximum switch current = I_{LIM} . The current in the switches is monitored by current limit comparators. Once the current in the upper switch exceeds the threshold of it's current limit comparator, it turns off and the lower switch is activated to ramp down the current in the switch inductor and upper switch. The upper switch can only turn on again, once the current has decreased below the threshold of its current limit comparator.

If the load continuously demands more current that what LTS8003 could provide, it cannot regulate the output voltage. Eventually under voltage protection will be triggered and shuts down the LTS8003 if Vout is too low.

Under Voltage Protection

Under voltage protection (UVP) is triggered and shuts down the converter if the output voltage is lower than 50% of its target level. The converter can only be set by POR of V_{IN} or toggling the EN pin.

Thermal Shutdown

As soon as the junction temperature, T_J, exceeds 150°C (typical) the device goes into thermal shutdown. In this mode, both upper and lower switches are turned-off. The device continues its operation when the junction temperature falls below the thermal shutdown hysteresis.

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25°C/W

20°C/W

20°C/W



Absolute Maximum Ratings (Note 1)

Input Supply Voltage (V _{IN})	-0.3V to 6.0V
LX	0.3V to $(V_{IN} + 0.3V)$, < 6.0V
Others	0.3V to 6.0V
ESD (Note 2)	
Human Body Mode	2kV
Machine Mode	200V
Thermal Information	
Continuous Junction Temperature Range	-40°C to 150°C
Storage Temperature Range	65°C to 150°C
Lead Temperature (Soldering, 10 second)	260°C
Package Thermal Resistance (Note 3)	
TSOT23, θ _{JA}	250°C/W

TSOT23, 0JC

WDFN2x2-6L, θ_{JC}

WDFN2x2-8L, θ_{JA}

TSOT23	0.4W
WDFN2x2-6L	0.74W
WDFN2x2-8L	0.74W

______135°C/W

Recommended Operation Conditions

Continuous Junction Temperature Range	-40°C to 120°C
Ambient Temperature Range	-40°C to 85°C
Input Voltage Range (VIN)	2.5V to 5.5V

- Note 1: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability and lifetime.
- Note 2: This device is sensitive to electrostatic discharge. Follow proper handling procedures.
- Note 3: The Thermal Resistance specifications are based on a JEDEC standard JESD51-3 single-layer PCB. θ_{JA} will vary with board size and copper area.
- Note 4: The maximum allowable power dissipation is a function of the maximum junction temperature, T_{J-MAX} , the junction-to-ambient thermal resistance, θ_{JA} , and the ambient temperature, T_A . The maximum allowable power dissipation at any ambient temperature is calculated using: $P_{D(MAX)} = (T_{D(MAX)} T_A)/\theta_{JA}$. The maximum power dissipation is determined using $T_A = 25^{\circ}C$, and $T_{J(MAX)} = 125^{\circ}C$.



Electrical Characteristics

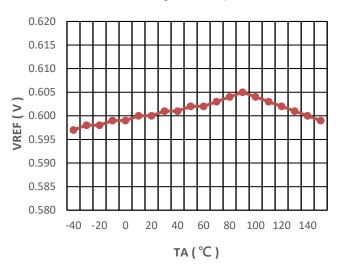
 $V_{IN} = V_{EN} = 3.6V$, and $T_A = 25^{\circ}C$ unless otherwise specified. External components $C_{IN} = 10uF$, $C_{OUT} = 10uF$, L = 2.2uH.

Parameters	Symbol	Condition	Min	Тур.	Max	Unit
Supply Input			•		•	
Supply Input Range	V _{IN}		2.5		5.5	V
Output Current	Іоит				1.2	Α
Shutdown Current	I _{SD}	$V_{EN} = 0V$		0.1	1	uA
Ouissant Current		MODE = 0V, V _{FB} = 0.65V		50		uA
Quiescent Current	ΙQ	MODE = V _{IN} = 3.6V, V _{OUT} = 1.8V		7		mA
Input Under Voltage Lockout Threshold	Vuvlo	V _{IN} rising		2.3	2.4	V
Input Under Voltage Lockout Hysteresis	Vuvhys	V _{IN} falling		200		mV
Power Switch						
Upper Switch On Resistance	_			240		mΩ
Lower Switch On Resistance	R _{DS(ON)}			180		mΩ
Upper Switch Current Limit	I _{LIM}		1.2	1.5		Α
Leakage Current into LX Pin	I _{LKG}	$2.5V \le V_{IN} \le 5.5V$, $0V \le V_{LX} \le V_{IN}$, $V_{EN} = 0V$	-1		1	uA
EN & MODE						
High Level Input Voltage	V _{IH}	2.5V ≤ V _{IN} ≤ 5.5V	1.4		VIN	٧
Low Level Input Voltage	VIL	2.5V ≤ V _{IN} ≤ 5.5V	0		0.4	V
EN Input Bias Current			-1		1	uA
MODE Input Bias Current		MODE = GND.		1	2	uA
POK#						
POK# Low Threshold		V _{FB} Rising		89		$%V_{REV}$
POK# High Threshold		V _{FB} Falling		86		$%V_{REF}$
POK# Deglitch Time	tdpok	V _{FB} Rising		12		us
Oscillator						
Oscillator Frequency	fosc	2.5V ≤ V _{IN} ≤ 5.5V	1.2	1.5	1.8	MHz
Maximum Duty Cycle		V _{FB} = 0.55V, V _{IN} = V _{OUT}	100			%
Output Voltage						
Adjustable Output Voltage Range	V _{OUT}		0.6		V _{IN}	V
Reference Voltage	V _{REF}		590	600	610	mV
Chip Enable Time	t _{EN}	Time from active EN to POK# low			500	us
Output Voltage Ram-up Time	tss	Time to ramp from 5% to 95% of Vout		100		us
Output Under Voltage Threshold	Vuv	V _{OUT} falling to percent of default value		50		%
Thermal Shutdown						
Thermal Shutdown Threshold				150		οС
Thermal Shutdown Hysteresis				20		οС

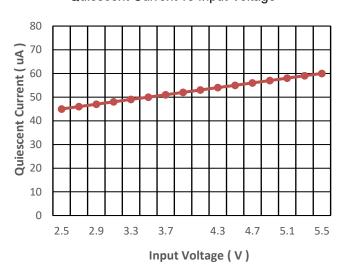


Typical Characteristic

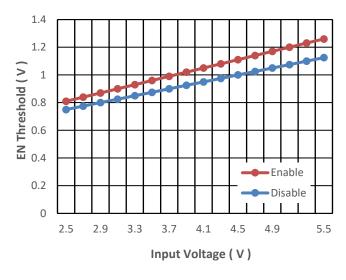
Reference Voltage vs Temperature



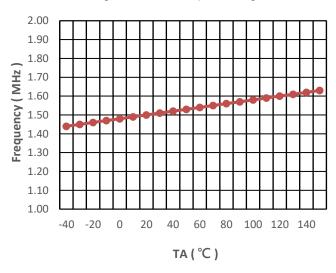
Quiescent Current vs Input Voltage



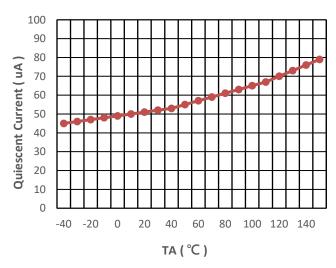
Enable Threshold vs Input Voltage



Charge Current vs Input Voltage



Quiescent Current vs Temperature





Application Information

Output Inductor Selection

Output inductor selection is usually based the considerations of inductance, rated current value, size requirements and DC resistance (DCR). The inductance is chosen based on the desired ripple current. Large value inductors result in lower ripple currents and small value inductors result in higher ripple currents.

Higher V_{IN} or V_{OUT} also increases the ripple current as shown in the equation below. A reasonable starting point for setting ripple current is $\Delta I_L = 180 \text{mA}$ (30% of 600mA). For most applications, the value of the inductor will fall in the range of 1uH to 10uH.

$$\Delta I_{L} = \frac{1}{f_{OSC} \times L_{OUT}} \times V_{OUT} \times (1 - \frac{V_{OUT}}{V_{IN}})$$

Maximum current ratings of the inductor are generally specified in two methods: permissible DC current and saturation current. Permissible DC current is the allowable DC current that causes 40°C temperature raise. The saturation current is the allowable current that causes 10% inductance loss. Make sure that the inductor will not saturate over the operation conditions including temperature range, input voltage range, and maximum output current. If possible, choose an inductor with rated current higher than 2.0A so that it will not saturate even under current limit condition.

The size requirements refer to the area and height requirement for a particular design. For better efficiency, choose a low DC resistance inductor. DCR is usually inversely proportional to size.

Different core materials and shapes will change the size/current and price/current relationship of an inductor. Toroid or shielded pot cores in ferrite or permalloy materials are small and don't radiate much energy, but generally cost more than powdered iron core inductors with similar electrical characteristics. The choice of which style inductor to use often depends on the price vs. size requirements and any radiated field/EMI requirements.

Input Capacitance

The LTS8003 draws pulsed current with sharp edges from the input capacitor resulting in ripple and noise at the input supply voltage. A minimum 4.7uF X5R or X7R ceramic capacitor is highly recommended to filter the pulsed current. The input capacitor should be placed as near the device as possible to avoid the stray inductance along the connection trace. Y5V dielectrics, aside from losing most of their capacitance over temperature, they also become resistive at high frequencies. This reduces

their ability to filter out high frequency noise.

The capacitor with low ESR (equivalent series resistance) provides the small drop voltage to stabilize the input voltage during the transient loading. For input capacitor selection, the ceramic capacitors larger than 4.7uF is recommend. The capacitor must conform to the RMS current requirement. The maximum RMS ripple current is calculated as:

$$I_{\text{IN(RMS)}} = I_{\text{OUT(MAX)}} \times \frac{\sqrt{V_{\text{OUT}} \times (V_{\text{IN}} - V_{\text{OUT}})}}{V_{\text{IN}}}$$

This formula has a maximum at $V_{\text{IN}} = 2xV_{\text{OUT}}$, where $I_{\text{IN(RMS)}} = I_{\text{OUT}(\text{MAX})/2}$. This simple worst-case condition is commonly used for design because even significant deviations do not offer much relief. Note that the capacitor manufacturer's ripple current ratings are often based on 2000 hours of life. This makes it advisable to further derate the capacitor, or choose a capacitor rated at a higher temperature than required. Always consult the manufacturer if there is any question.

Output Capacitor Selection

The LTS8003 is specifically design to operate with minimum 10uF X5R or X7R ceramic capacitor. The value can be increased to improve load/line transient performance.

The ESR of the output capacitor determines the output ripple voltage and the initial voltage drop following a high slew rate load transient edge. The output ripple voltage can be calculated as:

$$\Delta V_{OUT} = \Delta I_{C} \times (\text{ESR} + \frac{1}{8 \times f_{OSC} \times C_{OUT}})$$

Where fosc = operating frequency, C_{OUT} = output capacitance and ΔI_{C} = ΔI_{L} = ripple current in the inductor.

The ceramic capacitor with low ESR value provides the low output ripple and low size profile. Connect a 10uF ceramic capacitor at output terminal for good performance and place the input and output capacitors as close as possible to the device.

Thermal Information

Implementation of integrated circuits in low-profile and fine-pitch surface-mount packages typically requires special attention to power dissipation. Many system-dependent issues such as thermal coupling, airflow, added heat sinks and convection surfaces, and the presence of other heat-generating components affect the power-dissipation limits of a given component.



For continuous operation, do not exceed absolute maximum operation junction temperature. The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surroundings airflow and temperature difference between junctions to ambient. The maximum power dissipation can be calculated by following formula:

$$P_{D(MAX)} = \frac{(T_{J(MAX)} - T_A)}{\theta_{JA}}$$

Where $T_{J(MAX)}$ is the maximum operation junction temperature, T_A is the ambient temperature and the θ_{JA} is the junction to ambient thermal resistance. For recommended operating conditions specification of the LTS8003, The maximum junction temperature is 125°C.

The junction to ambient thermal resistance θ_{JA} is layout dependent. Three basic approaches for enhancing thermal performance are listed below:

- Improving the power dissipation capability of the PCB design
- Improving the thermal coupling of the component to the PCB by soldering the Exposed Pad.
- Introducing airflow in the system

For WDFN2x2-6L or 8L package, the thermal resistance θ_{JA} is 135°C/W on the standard JEDEC 51-3 single layers thermal test board. The maximum power dissipation at T_A = 25°C can be calculated by following formula:

$$P_{D(MAX)} = \frac{(125^{\circ}C - 25^{\circ}C)}{135^{\circ}C/W} = 0.74W$$

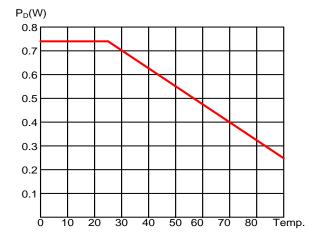


Figure 1: De-rating curve with ambient temperature on the maximum power dissipation allowed.

PCB Layout Consideration

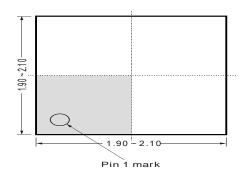
High switching frequencies and relatively large peak currents make the PCB layout a very important part of switching mode power supply design. Good design minimizes excessive EMI on the feedback paths and voltage gradients in the ground plane, both of which can result in instability or regulation errors. Follow the PCB layout guidelines for optimal performance of LTS8003.

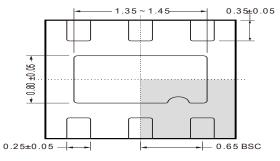
- 1. For the main current paths, keep their traces short, direct and wide. This results in low trace resistance and low parasitic inductance.
- 2. Put the input/output capacitors as close as possible to the device pins (VIN and GND).
- LX node is with high frequency voltage swing and should be kept small area. Keep analog components away from LX node to prevent stray capacitive noise pick-up.
- Connect feedback network behind the output capacitors. Place the feedback components near the LTS8003 and keep the loop area small.
- A ground plane is preferred, but if not available, keep the signal and power grounds separated with small signal components returning to the GND pin at one point. They should not share the high current path of C_{IN} or C_{OUT}.
- 6. Flood all unused areas on all layers with copper. Flooding with copper will reduce the temperature rise of power components. These copper areas should be connected to V_{IN} or GND.

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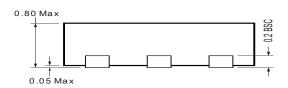


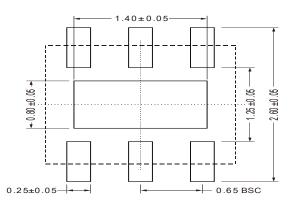
Package Information – WDFN2x2-6L





Bottom View - Exposed Pad



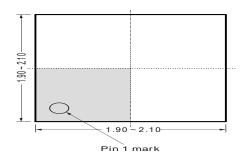


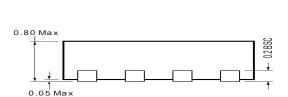
Recommended Solder Pad Pitch and Dimensions

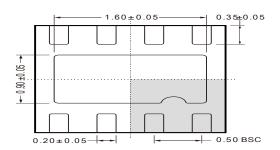
KG-WDFN2x2-6L-20120706



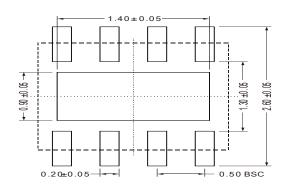
Package Information - WDFN2x2-8L







Bottom View - Exposed Pad



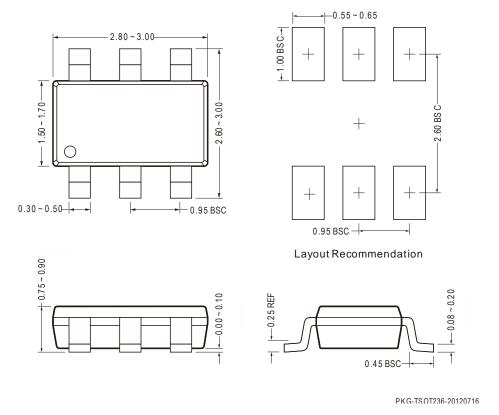
Recommended Solder Pad Pitch and Dimensions

PKG-WDFN2x2-6L-20120713

This package confirms to JDEC MS-012, Variation AA, Issue All dimensions are in millimeters.



Package Information - TSOT23-6



This package confirms to JDEC MS-012, Variation AA, Issue All dimensions are in millimeters.

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